SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688, SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

- Compares Two-8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- Hysteresis at P and Q Inputs
- 'LS682 has 20-kΩ Pullup Resistors on the Q Inputs
- SN74LS686 and 'LS687 . . . JT and NT 24-Pin, 300-Mil Packages

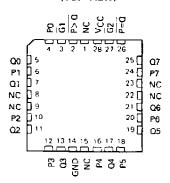
TYPE	P = Q	P > 0	OUTPUT	QUTPUT	20-kΩ
L	r = u	r > u	ENABLE	CONFIGURATION	PULLUP
'LS682	yes	yes	no	totem-pole	yes
'L\$684	yes	yes	no	totem-pole	no
'LS685	γ€ 5	yes	na	open-collector	no
SN74LS686	yes	yes	yes	totem-pole	no
'LS687	yes	yes	yes	open-collector	no
'LS688	yes	no	yes	totem-pole	no

SN54LS687 . . . JT PACKAGE SN74LS686, SN74LS687 . . . DW OR NT PACKAGE

(TOP VIEW)

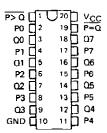
P> a M		т. Ъ	
	1	/ 24 L)	⊻cc
Ğ1 🔯	2	23 🖺	G2
P0 ☐	3	22	P=Q
00 [4	21	Ω7
P1 ☐	5	20	P7
O1 [6	19	NC
NC 🗌	7	18	Q5
P2 🔲	8	17	P6
02 🛚	9	16	Q5
P3 🗍	10	15[P5
o3 🗂	11	14	Q4
GND 🗌	12	13	P4

\$N54LS687 . . . FK PACKAGE (TOP VIEW)

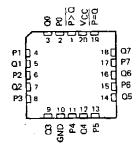


NC-No internal connection

\$N54L\$682, \$N54L\$684, \$N54L\$685 . . . J PACKAGE \$N74L\$682, \$N74L\$684, \$N74L\$685 . . . DW OR N PACKAGE (TOP VIEW)

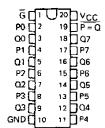


SN54LS682, SN54LS684, SN54LS685 . . . FK PACKAGE (TOP VIEW)

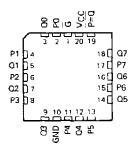


SN54LS688 . . . J PACKAGE SN74LS688 . . . DW OR N PACKAGE

(TOP VIEW)



SN54LS688 . . . FK PACKAGE (TOP VIEW)





SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688 SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

description

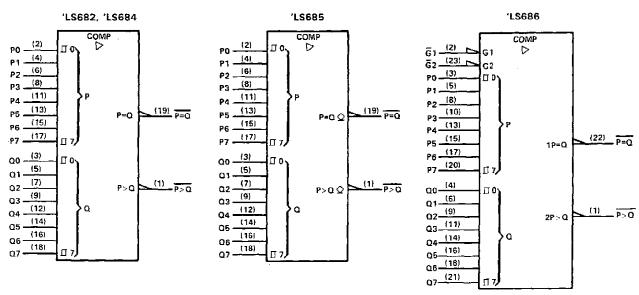
These magnitude comparators perform comparisons of two eight-bit binary or BCD words. All types provide $\overline{P}=\overline{Q}$ outputs and all except 'LS688 provide $\overline{P}>\overline{Q}$ outputs as well. The 'LS682, 'LS684, 'LS685, and 'LS688 have totem-pole outputs, while the 'LS685 and 'LS687 have open-collector outputs. The 'LS682 features 20-k Ω pullup termination resistors on the Q inputs for analog or switch data.

FUNCTION TABLE

	INPUTS		OUTI	PUTS
DATA	ENAB	ES	P=0	P>Q
P, Q	Ğ, <u>G1</u>	G2		.,,,
P=Q	L	Х	L	н
P>Q	×	L	н	L
P <q< td=""><td>х</td><td>×</td><td>н</td><td>Н_</td></q<>	х	×	н	Н_
P = Q	Н	X	Н	Н
P>Q	×	Н] н	Н
×	Н] н	Н	н

- NOTES: 1. The last three lines of the function table applies only to the devices having enable inputs, i.e., 'LS686 thru 'LS688.
 - The P<Q function can be generated by applying the P − Q and P > Q outputs to a 2-input NAND gate.
 - 3. For 'LS686 and 'LS687, \overline{G} 1 enables $\overline{P} = \overline{Q}$ and \overline{G} 2 enables $\overline{P} > \overline{Q}$.

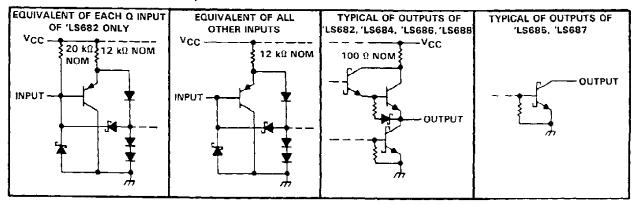
logic symbols†



 † These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

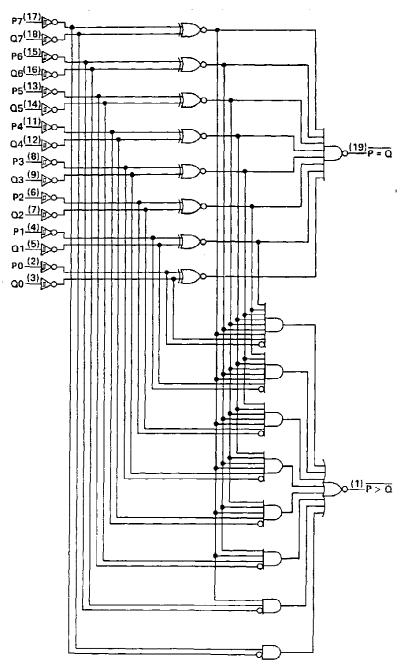
logic symbols† (continued) 'L\$687 'L\$688 COMP COMP 12) <u>G (1)</u> ãi. P0 (2) G1 Ğ2 (23) ► G2 ە □ (3) P1 (4) PO. ים ח (5) (6) P2 -P2 (8) P3 (B) P4 (11) (10) Р3-(13) (13) P5 -1151 (22) P=0 (15) P5 -19=0 ☆ P6 -P6 [17] P7 (17) (19) P=Q رد 🛚 P7 (20) 1P=Q □ 7, 00 (3) ים דו 00-(4) 01 (5) Πο, Q1 (6) 02 (7) Q2 (9) Q3 (9) (1) 03 (11) 2P -Q Q 04 (12) ò 04 (14) Q Q5 (14) Q5_(16) Q6• 06 (18) 07 (18) 07 (21)

schematics of inputs and outputs



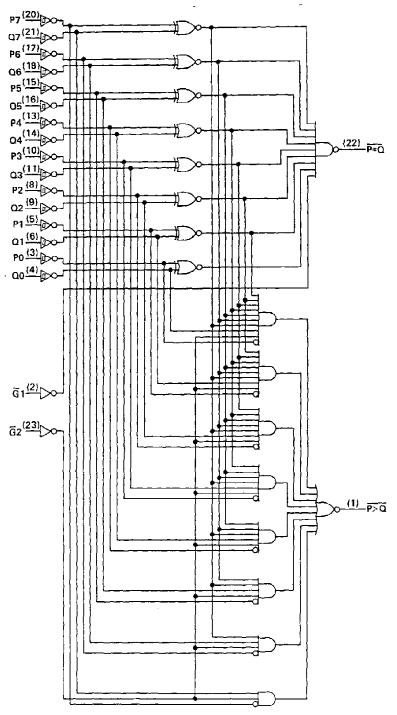
[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

'LS682, 'LS684, 'LS685 logic diagram (positive logic)



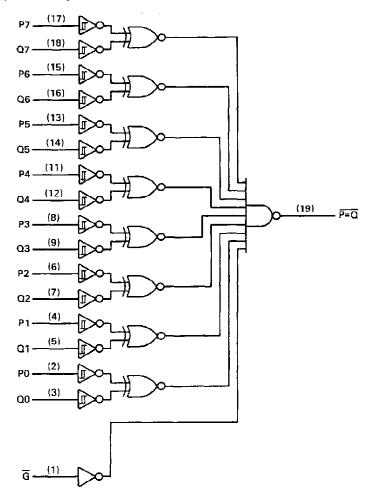
Pin numbers shown are for DW, J, and N packages.

'LS686, 'LS687 logic diagram (positive logic)



Pin numbers shown are for DW, JT, and NT packages.

'LS688 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		. 7 V
Input voltage: Q inputs of 'LS682		5.5 V
All other inputs		
Off-state output voltage: 'LS685, 'LS687		
Operating free-air temperature range:		
SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688 55	o°C to 1	125°C
SN74LS682, SN74LS684 thru SN74LS688	Q°C to	70°C
Storage temperature range65	o°C to 1	150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM POLE OUTPUTS

recommended operating conditions

		SN54LS	3′	s	N74LS		UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	>
High-level output current, IOH			-400			-400	μΑ
Low-level output current, IOL			12			24	mA
Operating free-air temperature, TA	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	Low-level input voltage + -VT - Hysteresis P or Q inputs Input clamp voltage H High-level output voltage Low-level output voltage Input current at maximum			************		SN54LS	3'	S	N74LS	•	
	PARAMETE	iR j	TEST CO	NDITIONS [†]	MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level inp	ut voltage			2	 '		2			٧
V _{IL}	Low-level inpu	ut voltage					0.7			0.8	V
VT+-VT-	Hysteresis	P or Q inputs	V _{CC} = MIN			0.4			0.4		V
VIK	Input clamp v	oltage	VCC = MIN.	ij = -18 mA			-1.5			- 1.5	>
∨он	High-level out	put voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	$V_{1H} = 2 V$, $I_{OH} = -400 \mu A$	2.5			2.7			٧
Vol	Low-level out	out voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	IOL = 12 mA		0.25	0.4		0.25	0.4	V
	<u> </u>		V _{IL} = V _{IL} max	ioL = 24 mA					0.35	0.5	
1,	Input current	Q inputs, 'LS682	VCC = MAX,	V ₁ = 5.5 V			0.1			0.1	mA
, 		All other inputs	V _{CC} = MAX,	V ₁ = 7 V			0.1				
ηн	High-level inp	ut current	V _{CC} = MAX.	V ₁ = 2.7 V			20			20	μA
ls.	Low-level	Q inputs, 'LS682'	V _{CC} = MAX,	V 0.4.V			-0.4			-0.4	mΑ
اا ا	input current	All other inputs	ACC = IAIWY	VI = 0.4 V			-0.2			-0.2	111.6
los§	Short-circuit o	output current	V _{CC} = MAX,	V _O = 0	- 20		- 100	- 20		- 100	mA
	• •	'LS682				42	70		42	70	
[C	'LS684	17. 1459	Con Nove 4		40	65		40	65	_^
lcc	Supply current 'LS686	VCC = MAX, S	4X, See Note 1		44	75		44	75	mA 5	
		'LS688				40	65		40	65	

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} \approx 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 1: ICC is measured with any G inputs grounded, all other inputs at 4.5 V, and all outputs open.

SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER†	FROM	TΟ	TEST	'LS68	2	'LS68	4	'LS68	3	'LS6	88	UNIT
PANAMETER.	(INPUTS)	(OUTPUT)	CONDITIONS	MIN TYP	MAX	MIN TYP	MAX	MIN TYP	MAX	MIN TY	P MAX	UNIT
tPLH	P	P≖Q		13	25	15	25	13	25	1	2 18	
^t PHL		r≖u.		15	25	17	25	20	30	1	7 23	ns
^t PLH	α	$\overline{P} = \overline{Q}$	i	14	25	16	25	13	25	1	2 18	
^t PHL	u	r=u	D 667.0	15	25	15	25	21	30	1	7 23	ns
^t PLH	<u>ট,</u> ট্র1	P=Ω	$R_{L} = 667 \Omega,$ $C_{L} = 45 \text{m}^{2}$					11	20	1	2 1E	3
^t PHL	G, G1	, r=u	$C_L = 45 \text{ pF},$					19	30	1	3 20	ns
_ t∍L'H	Р	D. 0	All other	20	30	22	30	19	30			
tpHL	,	P>Q	inputs low,	15	30	17	30	15	30			ns
[†] PLH	Q	P>Q	See Note 2	21	30	24	30	18	30			1
tPHL .	u	F>Q		19	30	20	30	19	30			n\$
tplH_	Ĝ2	<u> </u>						21	30			
tpHI	2ن	₽>Ω						16	25			ns

 $^{^{\}dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS685, SN54LS687 SN74LS685, SN74LS687, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

• • • • • • • • • • • • • • • • • • •		SN54LS	,	s	N74LS	'i	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNI
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	V
High-level output current, VOH			5.5			5.5	V
Low-level output current, IQL			12			24	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETE		TEOT 0011	uriono!	5	SN54L	3'	S	N74LS	•	UNIT
	PARAMETE	К	TEST CONI	DITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONIT
VIH	High-level in	put voltage			2			2			٧
VIL	Low-level int	out voltage					0.7			8.0	V
V _{T+} -	V _{T -} Hysteresis	P or Q inputs	VCC = MIN			0.4			0.4		٧
Vik	Input clamp	voltage	VCC = MIN,	$l_{\parallel} = -18 \text{ mA}$			- 1.5			-1.5	V
Іон	High-level or	itput voltage	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, V _{OH} = 5.5 V			250			100	μΑ
Vol	Low-level ou	tnut voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
-0.			VIL = VILmax	l _{OL} = 24 mA	j				0.35	0.5	
_կ			VCC = MAX,	V ₁ = 7 V			0.1			0.1	mA
_'IH	High-level in	put current	V _{CC} = MAX,	$V_1 = 2.7 V$			20			20	μΑ
I _{IL}	Low-level in:	out current	V _{CC} ≈ MAX,	V ₁ = 0.4 V			-0.2			-0.2	mA
	Supply	'LS685	V MAY	Con Note 1		40	65		40	65	4
CC	current	'LS687	$V_{CC} = MAX$	See Note 1		44	75		44	75	mA

[†]For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. NOTE 1: I_{CC} is measure with any \overline{G} inputs grounded, all other inputs at 4.5 V, and all outputs open.

8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH OPEN-COLLECTOR OUTPUTS

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM	то	TEAT COMMITTALIA		'LS685			'L\$687		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONIT
tPLH	P	P=Q			30	45		24	35	ns
†PHL	r)			19	35		20	30	115
tpLH	Q	P≂Œ			24	45		24	35	
tPHL .			9 667.0		23	35		20	30	ns
tpLH	ਰ, ਰ 1	P=Q	$R_L \approx 667 \Omega$					21	35	
TPHL	9, 91]	Cլ = 45 pF,					18	30	ns
t _{PLH}		P>Q	All other		32	45		24	35	
^t PHL	P	P>u	inputs low,		16	35		16	30	ns
^t PLH	α	P>Q	See Note 2		30	45		24	35	
tPHL	u	Pou			20	35		16	30	ns
tPLH	<u>G</u> 2	5.0						24	35	
^t PHL	G∠	P>0						15	30	ns

 $^{^{\}dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
8415101RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Samples
8415101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
8415101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
84152012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84152012A SNJ54LS 684FK	Samples
8415201RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415201RA SNJ54LS684J	Samples
84153012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84153012A SNJ54LS 688FK	Samples
8415301RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415301RA SNJ54LS688J	Samples
8415301SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415301SA SNJ54LS688W	Samples
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS682J	Samples
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS682J	Samples
SN54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS684J	Samples
SN54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS688J	Samples
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Samples

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sam
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS682	Sam
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS682N	Sam
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS682N	Sam
SN74LS682NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS682	San
SN74LS682NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS682	Sar
SN74LS684DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS684	Sar
SN74LS684DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS684	Sar
SN74LS684N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS684N	Sar
SN74LS684NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS684N	Sar
SN74LS684NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS684	Sar
SN74LS688DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS688	Sai
SN74LS688DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS688	Sar
SN74LS688DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS688	Sar
SN74LS688N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS688N	Sar
SN74LS688NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS688N	Sar
SN74LS688NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS688	Sar
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Sar
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101RA SNJ54LS682J	Sar

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415101SA SNJ54LS682W	Samples
SNJ54LS684FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84152012A SNJ54LS 684FK	Samples
SNJ54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415201RA SNJ54LS684J	Samples
SNJ54LS688FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84153012A SNJ54LS 688FK	Samples
SNJ54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415301RA SNJ54LS688J	Samples
SNJ54LS688W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415301SA SNJ54LS688W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) -

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS682, SN54LS684, SN54LS688, SN74LS682, SN74LS684, SN74LS688:

Catalog: SN74LS682, SN74LS684, SN74LS688

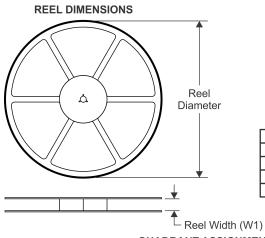
Military: SN54LS682, SN54LS684, SN54LS688

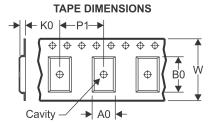
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

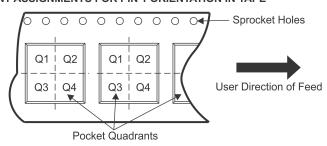
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

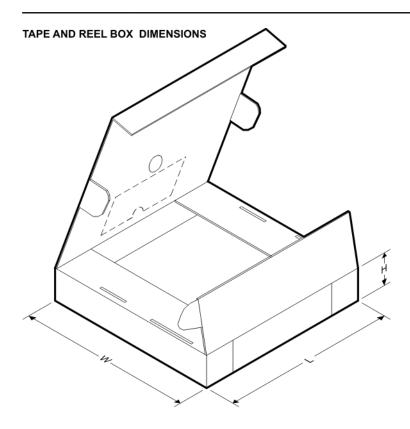
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS682DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS682NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS684DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS684NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS688NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

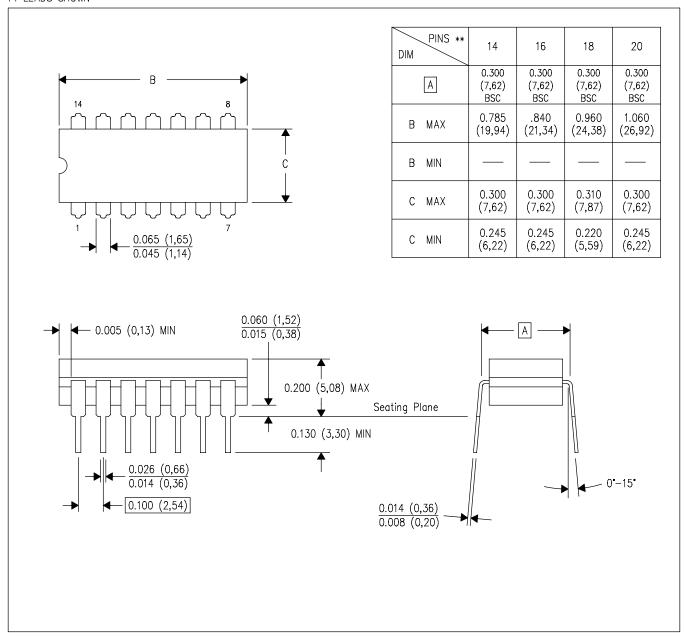
PACKAGE MATERIALS INFORMATION



*All dimensions are nominal

Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS682DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS682NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LS684DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS684NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LS688DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS688NSR	SO	NS	20	2000	367.0	367.0	45.0

14 LEADS SHOWN

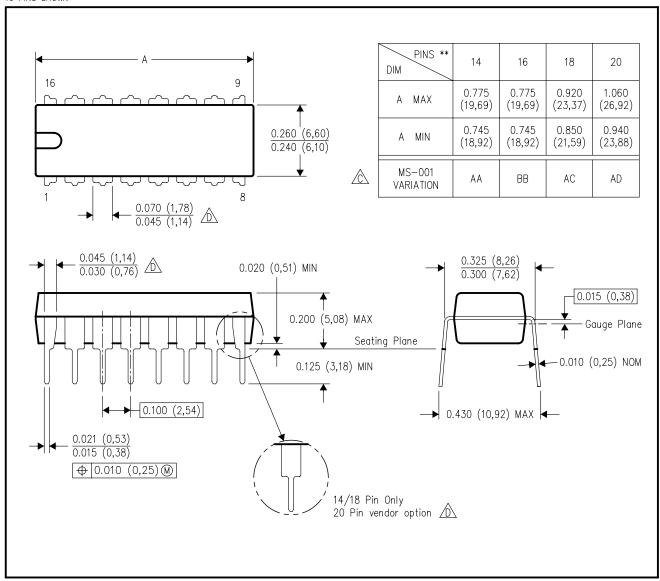


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

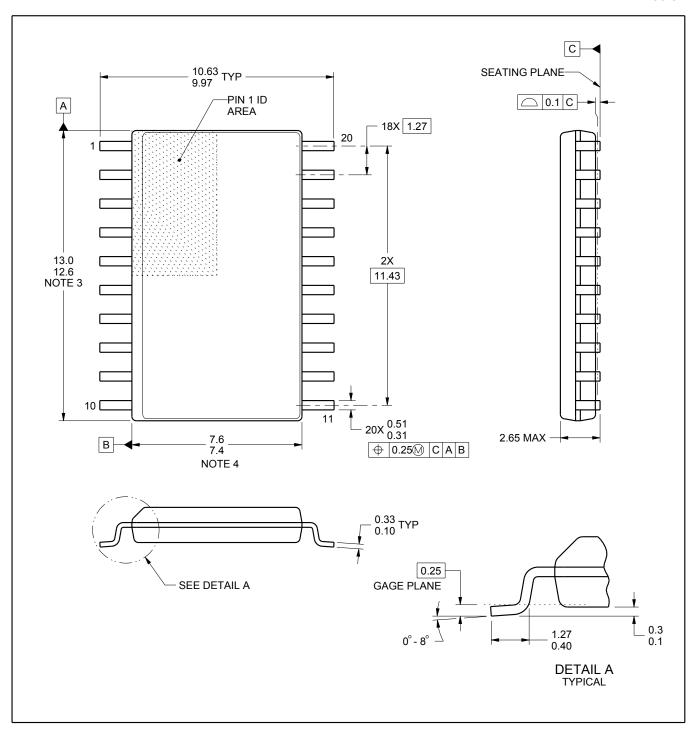
16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



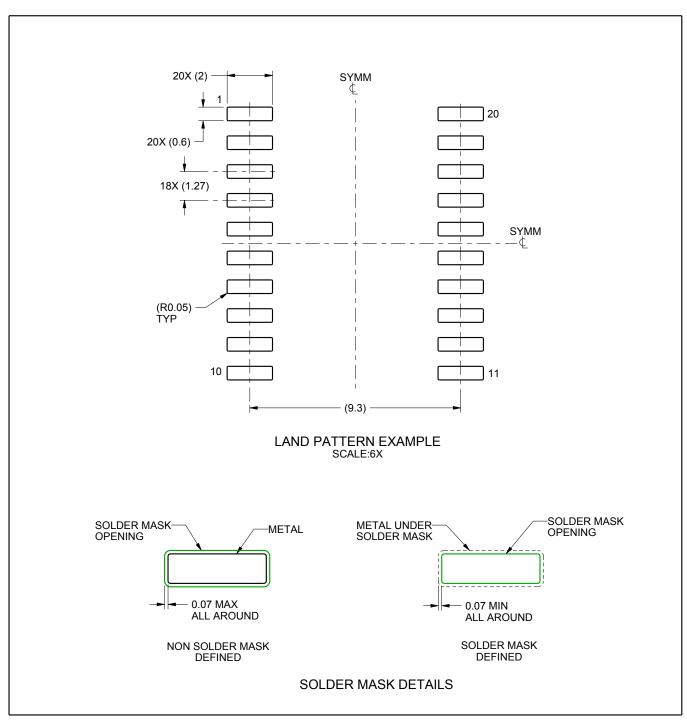
SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

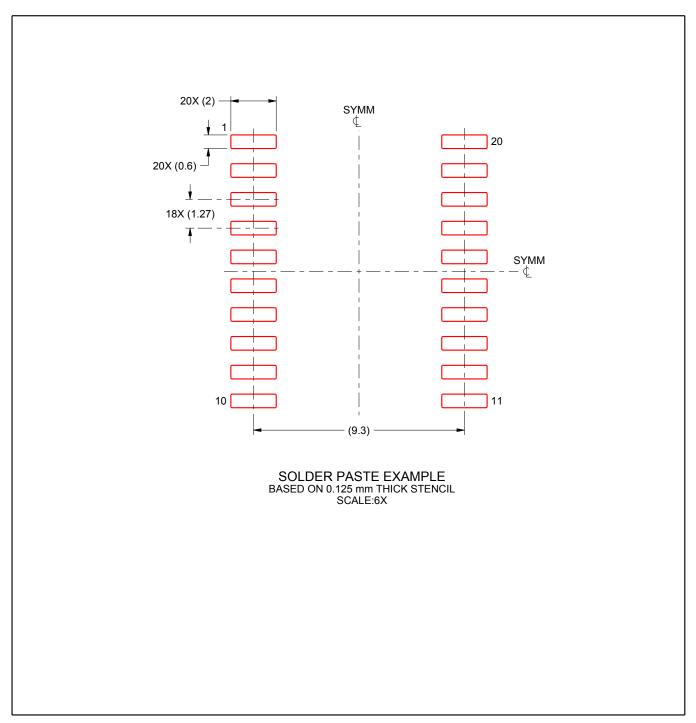
 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



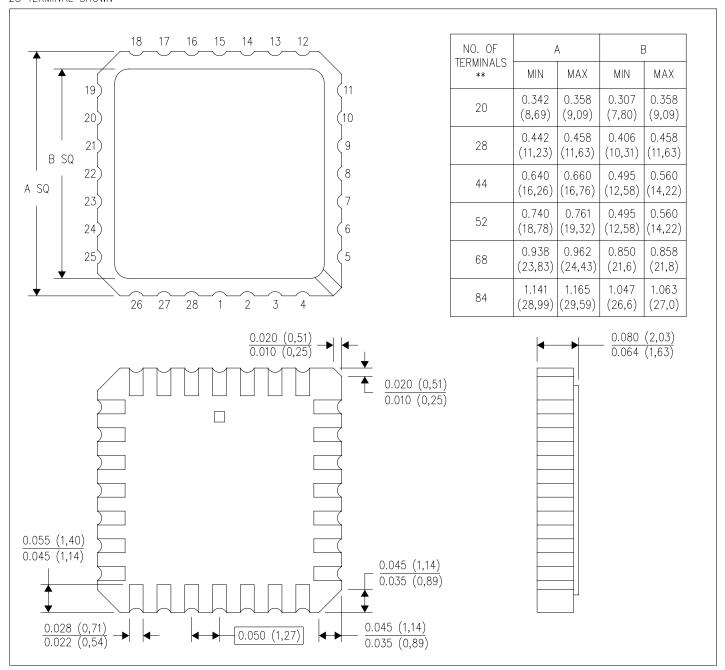
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



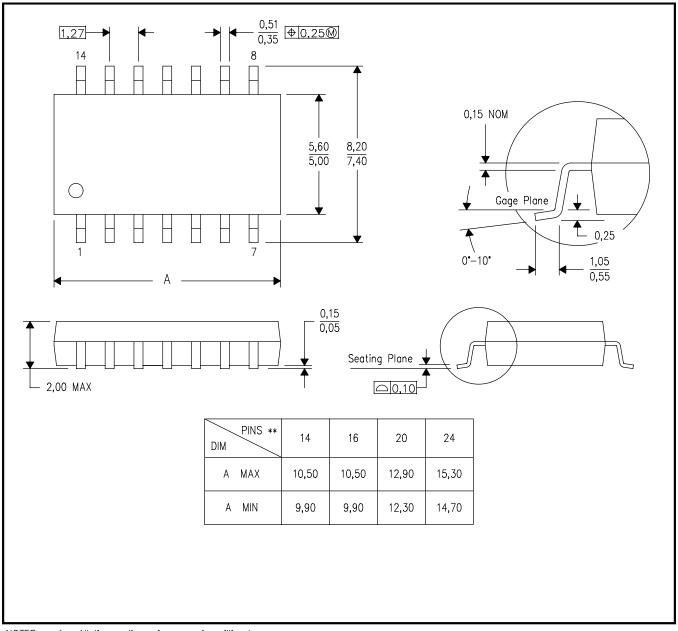
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

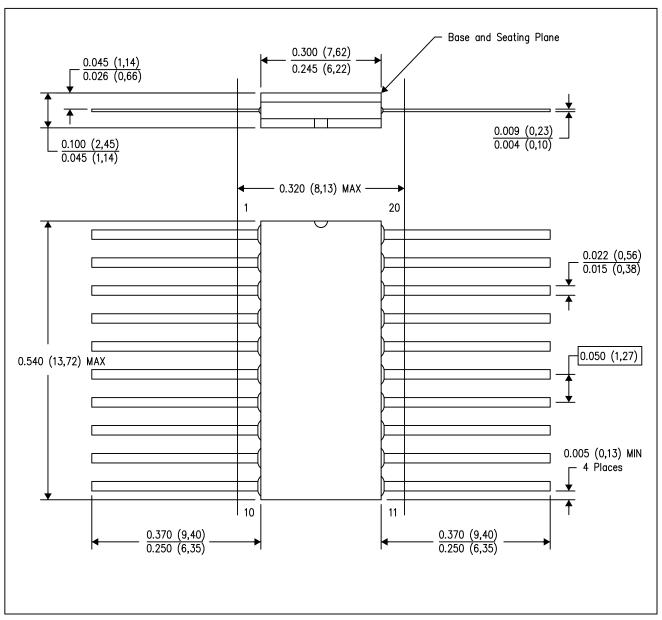
PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.

 C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20